MSDS Report

Report NO.: MOS-MG00001000227

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAA3134KL
Package Type :	WBFBP-03E

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	4.42%
Lead Frame	Copper	7440-50-8	96.498%	42.63%
	Iron	7439-89-6	2.300%	
	Lead	7439-92-1	0.002%	
	Phosphorus	7723-14-0	0.100%	
	Zinc	7440-66-6	0.100%	
	Silver	7440-22-4	1.000%	
Wire	Copper	7440-50-8	98.00%	3.55%
	Palladium	7440-05-3	1.90%	
	Gold	7440–57-5	0.10%	
Mold Compound	Epoxy Resin A	Trade secret	5%	47.00%
	Epoxy Resin B	Trade secret	1%	
	Phenol Resin	9003-35-4	5%	
	Silica(Amorphous) A	60676-86-0	80%	
	Silica(Amorphous) B	7631-86-9	5%	
	Metal Hydroxide	Trade secret	3%	
	Carbon Black	1333-86-4	1%	
Plating	Tin	7440-31-5	99.90%	2.40%
	Other	NA	0.10%	